



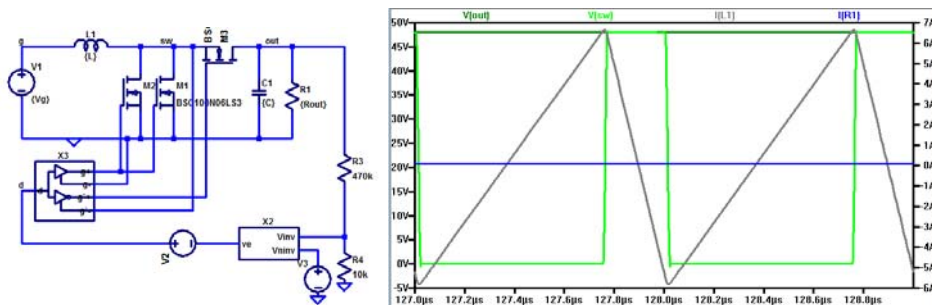
High Frequency Power Electronics

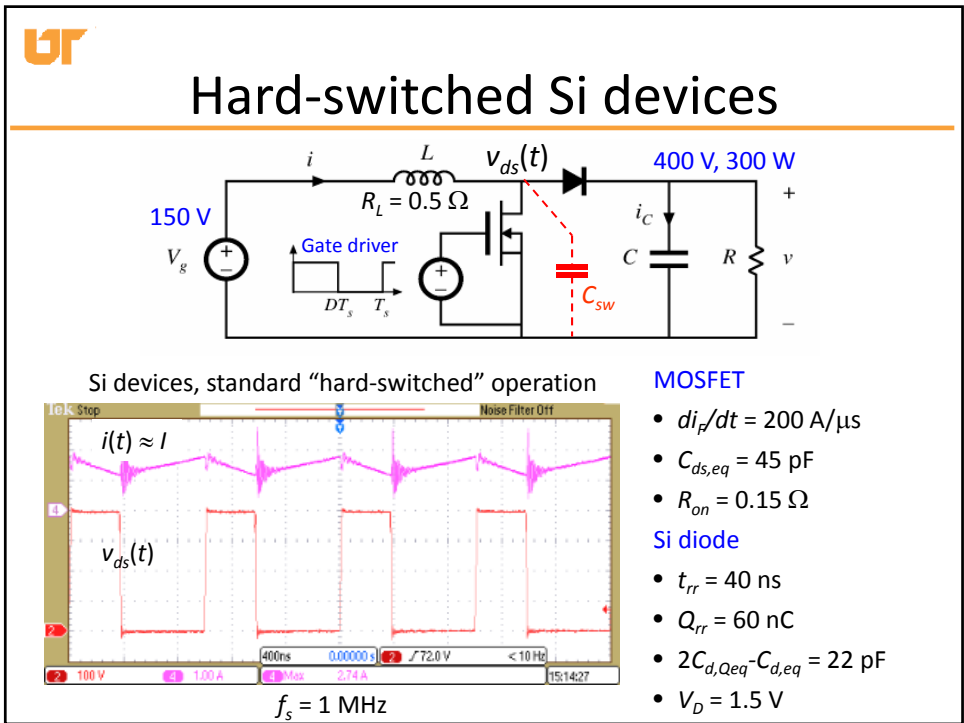
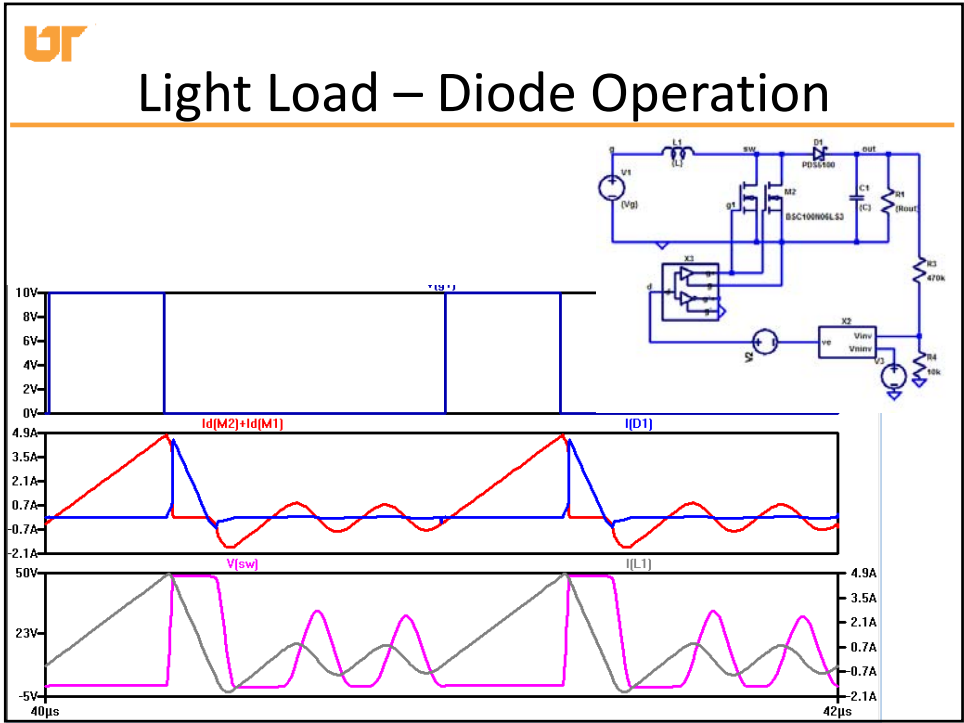
Prof. Daniel Costinett

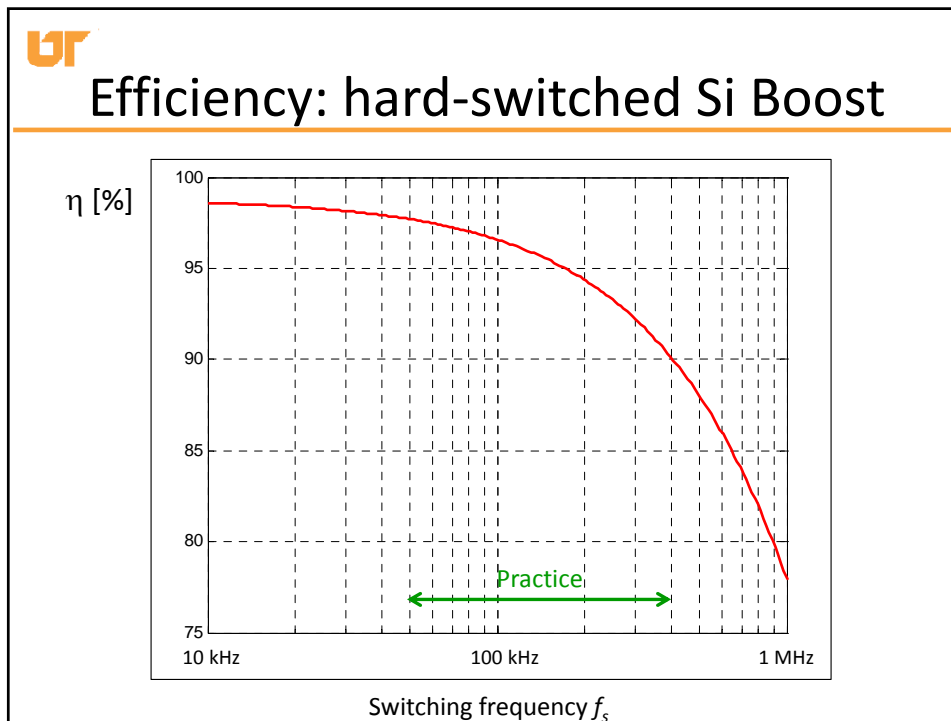
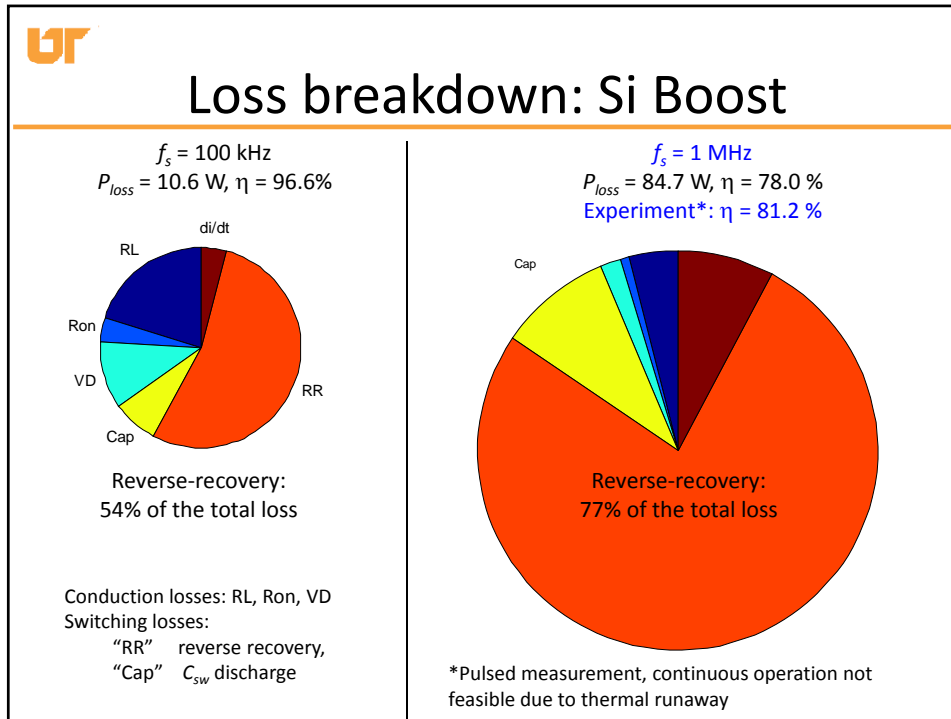
ECE 581 Lecture 4
August 27, 2014



Light Load Operation

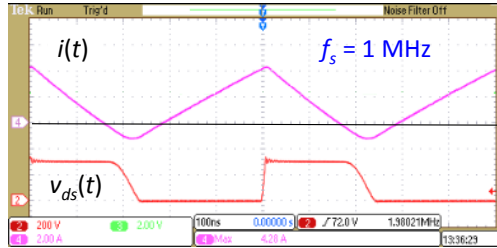




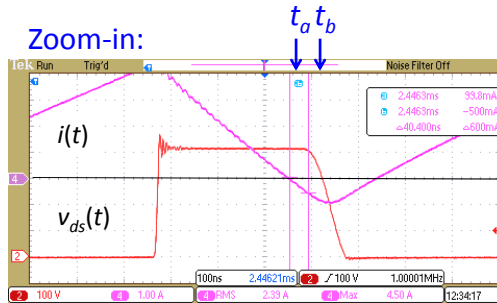




ZVS with Si diode



Zoom-in:

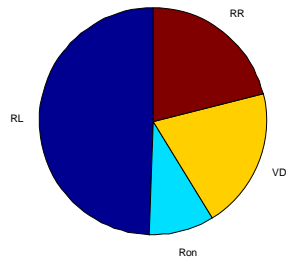


- ZVS turn-ON
 - Eliminated losses due to C_{sw} discharge during turn-ON transient
 - Eliminated losses due to MOSFET di_p/dt during turn-ON transient
- Diode reverse recovery still impacts the waveforms and losses
- Increased current ripple
 - Increased conduction losses (by >30%)
 - Increased dv_{ds}/dt upon turn-OFF, MOSFET turn-OFF speed is more important



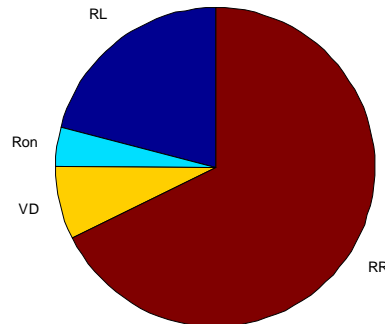
Loss Breakdown: Soft-Switched Si Boost

$f_s = 100 \text{ kHz}$
 $P_{loss} = 5.7 \text{ W}, \eta = 98.1\%$



Reverse-recovery:
 21% of the total loss

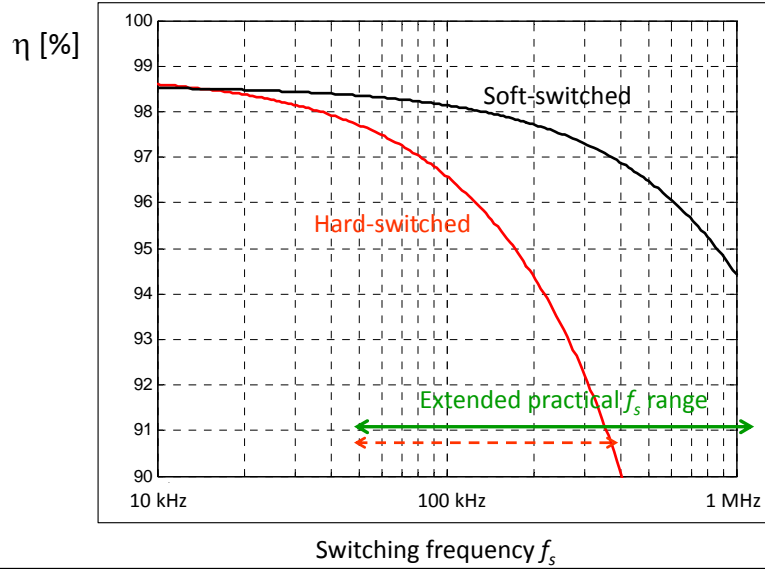
$f_s = 1 \text{ MHz}$
 $P_{loss} = 17.7 \text{ W}, \eta = 94.4 \%$
 Experiment: $\eta = 95.1 \%$



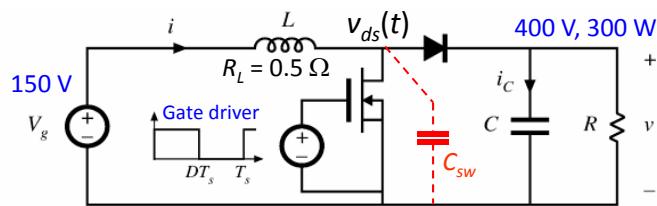
Reverse-recovery:
 68% of the total loss



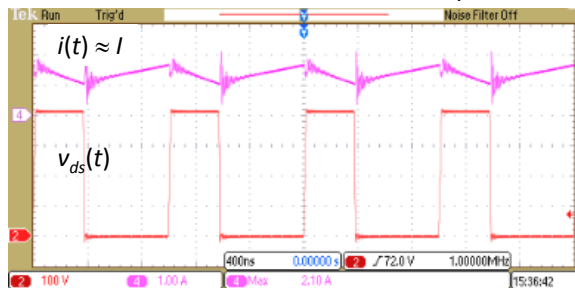
Efficiency: soft-switched Si Boost



Hard-Switched SiC Schottky Diode



SiC diode, standard "hard-switched" operation

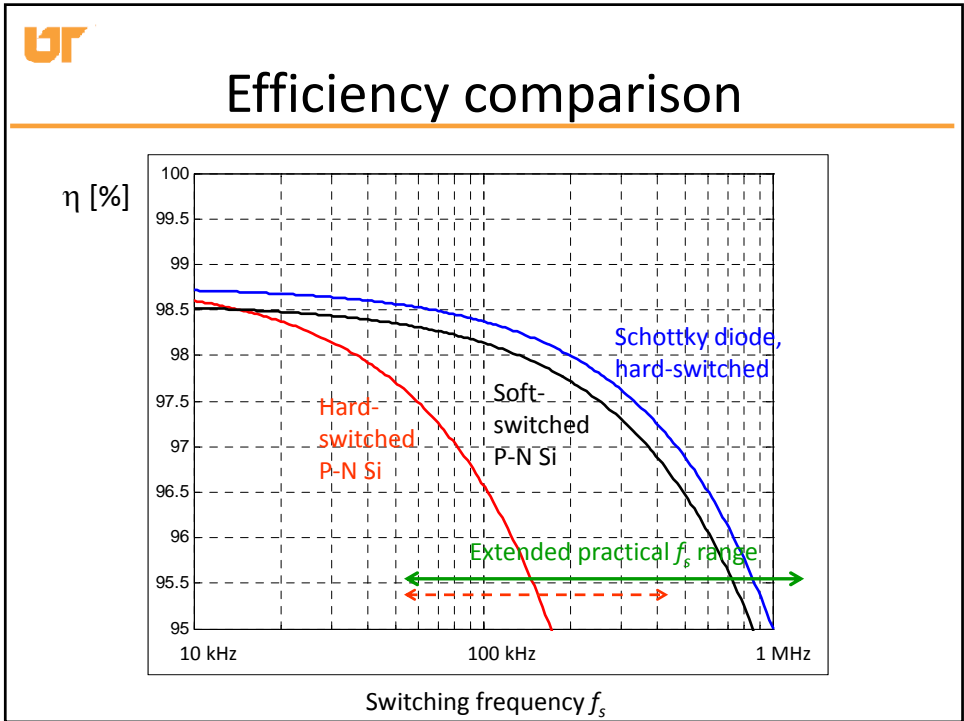
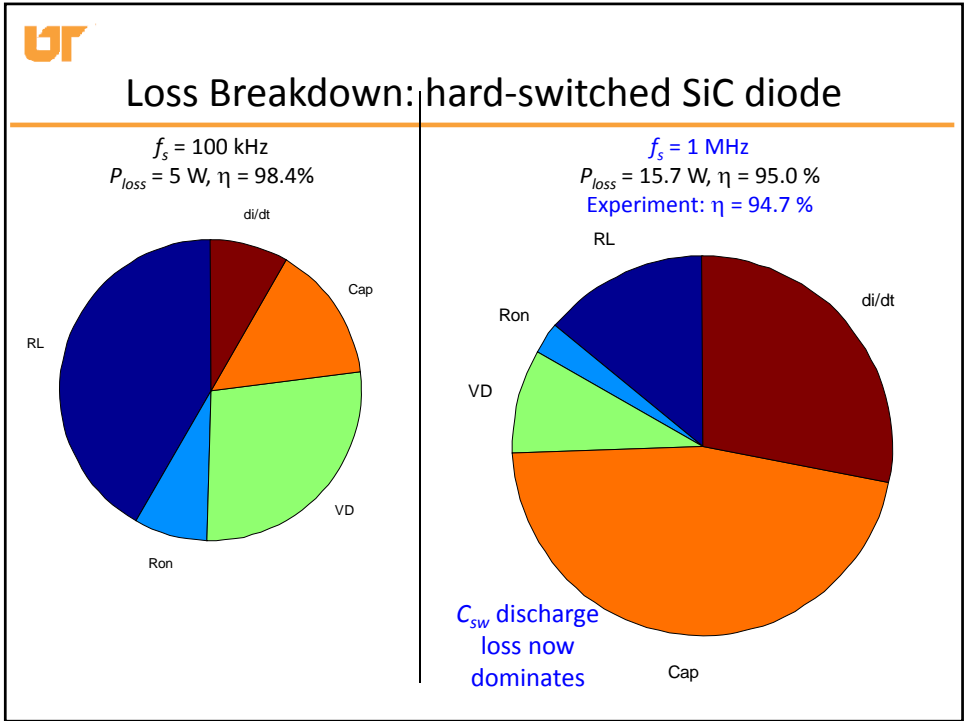


MOSFET

- $di_T/dt = 200 \text{ A}/\mu\text{s}$
- $C_{ds,eq} = 45 \text{ pF}$
- $R_{on} = 0.15 \Omega$

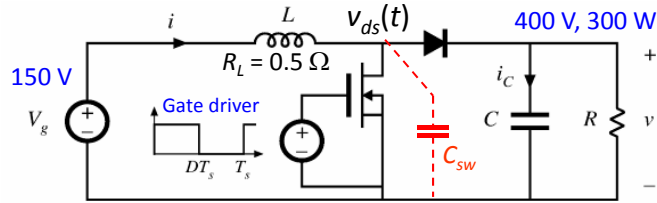
SiC diode

- $t_{rr} = 0, Q_{rr} = 0$
- $2C_{d,Req} - C_{d,eq} = 64 \text{ pF}$
- $V_D = 1.8 \text{ V}$

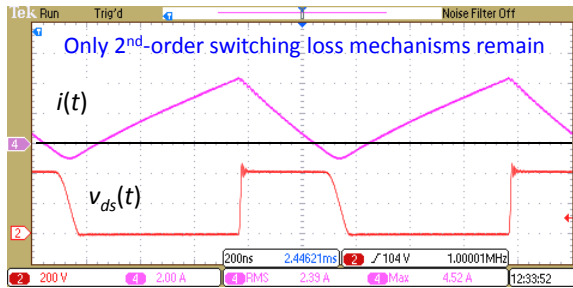




Soft-switched SiC Schottky diode



SiC diode, soft-switched operation



MOSFET

- $di_r/dt = 200 \text{ A}/\mu\text{s}$
- $C_{ds,eq} = 45 \text{ pF}$
- $R_{on} = 0.15 \Omega$

SiC diode

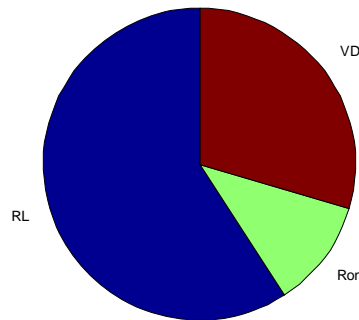
- $t_{rr} = 0, Q_{rr} = 0$
- $2C_{d,Qeq} - C_{d,eq} = 64 \text{ pF}$
- $V_D = 1.8 \text{ V}$

$f_s = 1 \text{ MHz}$



Soft-switched Boost with SiC diode

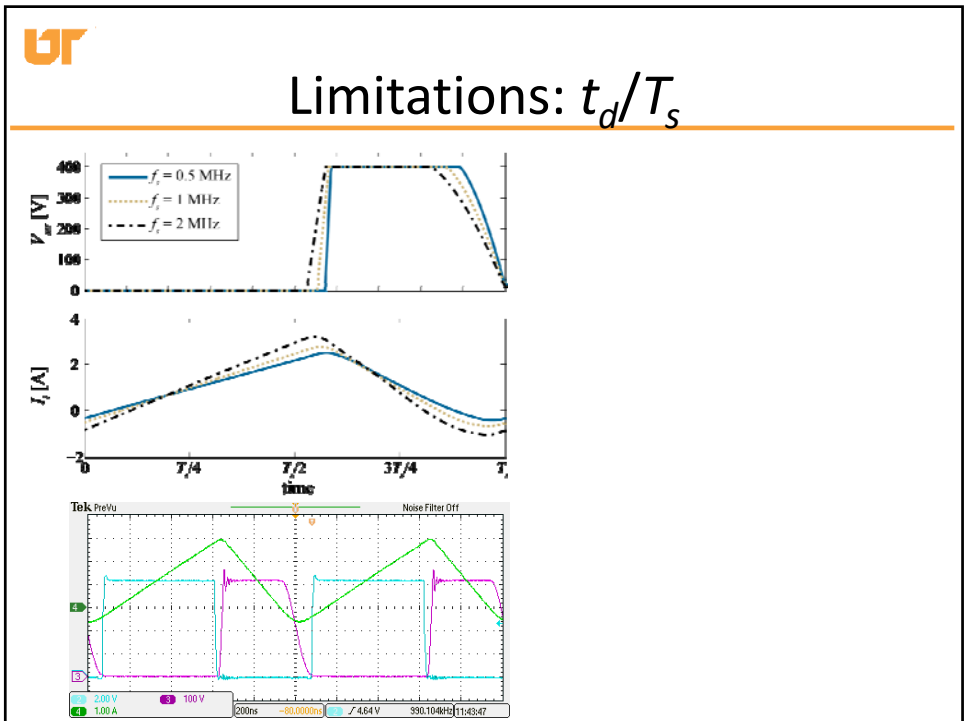
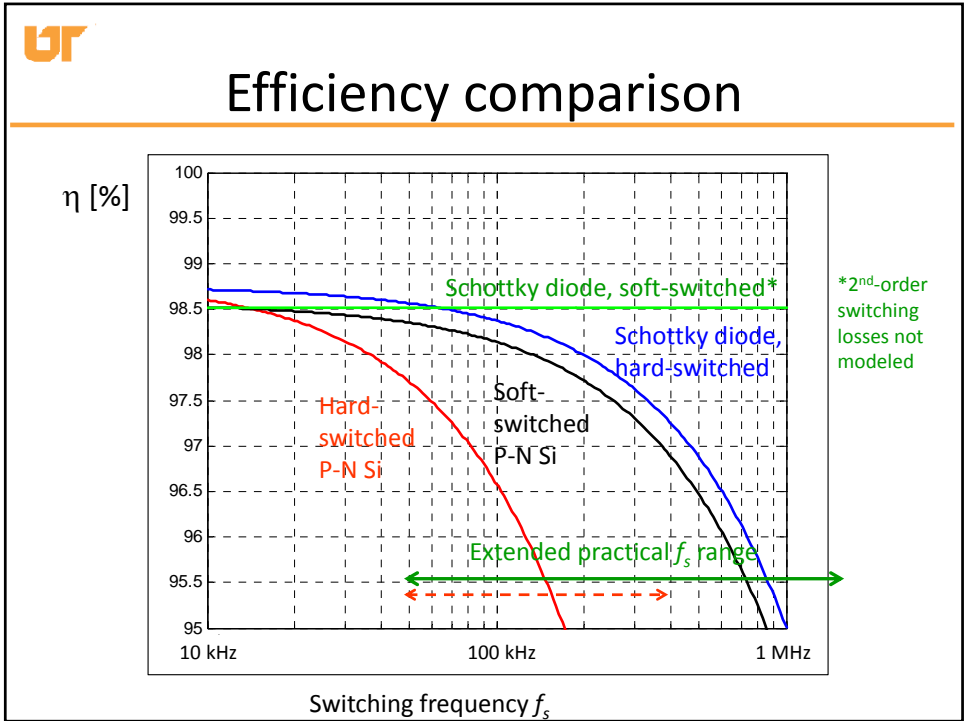
Conduction losses only, 2nd-order switching losses not included in the model



100 kHz or 1 MHz
98.5% efficiency
 $P_{loss} = 4.5 \text{ W}$

Experiments:

98.7% at 1 MHz
98.0% at 2 MHz





Limitations: 2nd Order Loss Mechanisms

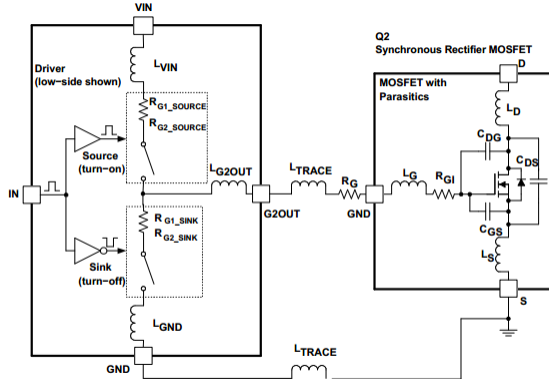


Figure 6. Low-Side Drive and MOSFET Parasitic Model

Texas Instruments, "Optimizing MOSFET Characteristics by Adjusting Gate Drive Amplitude"



Limitations: Gate Drive

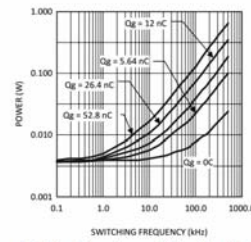
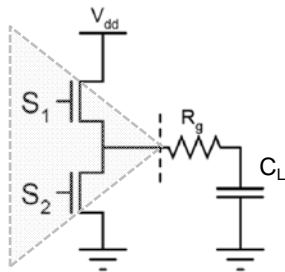


Figure 2. Gate Driver Power Dissipation (LO + HO) $V_{CC} = 12V$, Neglecting Diode Losses

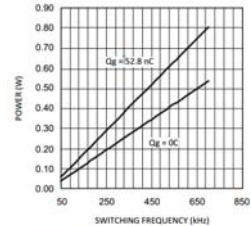
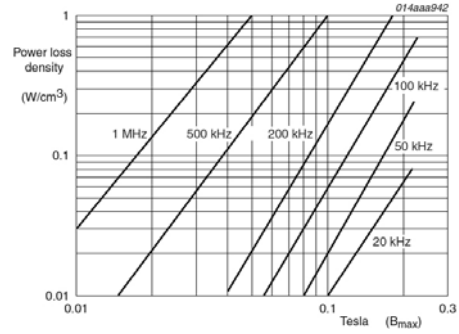
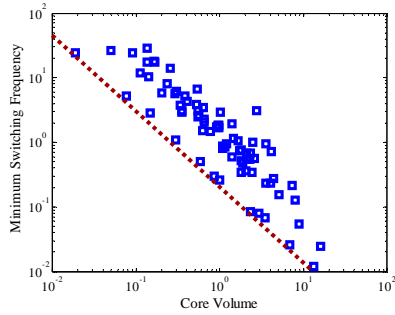


Figure 4. Diode Power Dissipation $V_m = 80V$

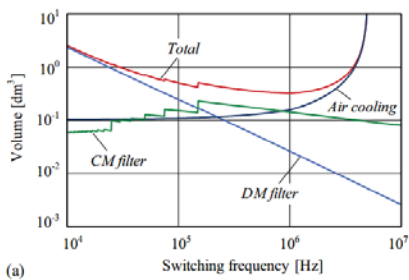
Texas Instruments, "Selection of External Bootstrap Diode for LM510X Devices"



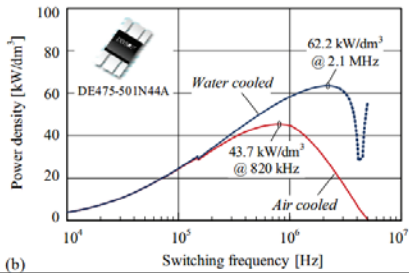
Limitations: Magnetics Design



Limitations: Thermal



(a)



(b)

Kolar, J.W.; Drofenik, U.; Biela, J.; Heldwein, M.L.; Ertl, H.; Friedli, T.; Round, S.D., "PWM Converter Power Density Barriers," *Power Conversion Conference - Nagoya, 2007. PCC '07*, vol., no., pp.P-9,P-29, 2-5 April 2007